



Tower Semiconductor Announces 2020 Annual Technical Global Symposium Online Event

October 14, 2020



Tower Semiconductor's 2020 Online TGS Event

Virtual Symposium brings the Company's leading team of experts directly to you at the comfort of your own home or office

Webinar presentations showcasing Company's premier Analog technologies, advanced design enablement and manufacturing solutions, including recent developments and future roadmaps for RF, High Performance Analog, Power Management and Sensor platforms

MIGDAL HAEMEK, Israel, October 14, 2020 – [Tower Semiconductor](#) (NASDAQ/TASE: TSEM), the leader in high-value analog semiconductor foundry solutions, today announced its online 2020 annual Technical Global Symposium. This online event consists of a series of webinars presenting the Company's premier analog technologies, manufacturing solutions and recent development across all of its platforms including RF & High Performance Analog, Power Management, Sensors, Aerospace & Defense as well as leading design enablement services and tools in joint sessions with selected EDA partners.

Similar to the Company's traditional TGS event format, the webinars will be presented by Tower's leading team of experts, with the added benefit of direct and easier access to interact online with the presenters and learn more about Company platforms and offerings. The sessions will provide detailed information on Company advanced SOI, SiGe, SiPho, Imaging and Non-Imaging sensors, MEMS and Power Management technologies, development roadmaps and manufacturing excellence. Each webinar will discuss Tower's best-in-class solutions addressing the current and future market needs of the IoT, 5G, networking, high-end imaging, sensing, automotive, industrial, and consumer markets.

Date	Topic	Presented by
November 9, 2020	Silicon Photonics and Advanced SiGe Technology for Optical Transceivers	Dr. Edward Preisler Director of Technology Development, RF & HPA Mr. Erez Sarig
November 10, 2020	The latest high voltage and high-power technologies	Director of Power Management Business Development & Marketing Japanese session by Mr. Akira Takeishi General Manager of Device Technology & Deputy Director of Power Management / Mixed Signal, TPSCo Dr. Assaf Lahav CIS Research & Development Expert and Fellow
November 12, 2020	Stacking BSI technology, iToF and dTOF for face recognition and next generation global shutter technology	Japanese session by Mr. Isao Miyanaga General Manager of Device Technology & Deputy Director of Image Sensor, TPSCo Dr. Amos Fenigstein Senior Director of CIS Research & Development, Sensors Business Unit
November 17, 2020	Under OLED and under LCD optical fingerprint sensors	

November 18, 2020	Process technology and PDK enhancements for Wireless Applications	Japanese session by Mr. Isao Miyanaga General Manager of Device Technology & Deputy Director of Image Sensor, TPSCo Dr. Paul Hurwitz Director of Device Technology, RF & HPA Myriam Buchbinder Senior Director of Process Engineering Research & Development
November 19, 2020	MEMS and NIS Technology for UV, radiation, temperature, and gas sensors	Prof. Yakov Roizin Director of Emerging Technologies & Fellow Dr. David Howard
November 23, 2020	Aerospace and Defense Technology Solutions	Executive Director & Fellow

For additional information, agenda and registration please visit the event page [here](#).

About Tower Semiconductor

Tower Semiconductor Ltd. (NASDAQ: TSEM, TASE: TSEM), the leader in high-value analog semiconductor foundry solutions, provides technology and manufacturing platforms for integrated circuits (ICs) in growing markets such as consumer, industrial, automotive, mobile, infrastructure, medical and aerospace and defense. Tower Semiconductor's focuses on creating positive and sustainable impact on the world through long term partnerships and its advanced and innovative analog technology offering, comprised of a broad range of customizable process platforms such as SiGe, BiCMOS, mixed-signal/CMOS, RF CMOS, CMOS image sensor, non-imaging sensors, integrated power management (BCD and 700V), and MEMS. Tower Semiconductor also provides world-class design enablement for a quick and accurate design cycle as well as Transfer Optimization and development Process Services (TOPS) to IDMs and fabless companies. To provide multi-fab sourcing and extended capacity for its customers, Tower Semiconductor operates two manufacturing facilities in Israel (150mm and 200mm), two in the U.S. (200mm) and three facilities in Japan (two 200mm and one 300mm) through TPSCo. For more information, please visit www.towersemi.com.

Safe Harbor Regarding Forward-Looking Statements

This press release includes forward-looking statements, which are subject to risks and uncertainties. Actual results may vary from those projected or implied by such forward-looking statements. A complete discussion of risks and uncertainties that may affect the accuracy of forward-looking statements included in this press release or which may otherwise affect Tower's business is included under the heading "Risk Factors" in Tower's most recent filings on Forms 20-F, F-3, F-4 and 6-K, as were filed with the Securities and Exchange Commission (the "SEC") and the Israel Securities Authority. Tower does not intend to update, and expressly disclaim any obligation to update, the information contained in this release.

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Attachments

- [TGS_2020_Final_101420](#)
- [Tower Semiconductor's Online TGS Event](#)



Source: Tower Semiconductor